

Low VF SMD Schottky Barrier Diode

FEATURES

- Low power loss, high current capability, low VF
- Surface mount device type
- Moisture sensitivity level (MSL): 1
- Packing code with suffix "G" means green compound (halogen-free)





SOD-323F



MECHANICAL DATA

- Case: Flat lead SOD-323F small outline plastic package
- Molding compound, UL flammability classification rating 94V-0
- Terminal: Matte tin plated, lead free,
- solderable per MIL-STD-202, Method 208 guaranteed
- High temperature soldering guaranteed : 260°C/10s- Polarity: Indicated by cathode band
- Weight: 4.6 ± 0.5 mgMarking Code: S8



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T _A =25°C unless otherwise noted)					
PARAMETER		SYMBOL	VALUE	UNIT	
Power Dissipation		P_{D}	200	mW	
Repetitive Peak Reverse Voltage		V_{RRM}	40	V	
Reverse Voltage		V_R	30	V	
Mean Forward Current		Ι _ο	30	mA	
Non-Repetitive Peak Forward Surge Current	60Hz for 1 Cyc.	I _{FSM}	0.2	Α	
Thermal Resistance (Junction to Ambient)	(Note)	$R_{\theta JA}$	500	°C/W	
Junction and Storage Temperature Range		T_J , T_STG	-40 to +125	°C	

	SYMBOL	TYP	MAX	UNIT	
Forward Voltage	I _F = 1 mA	V _F	-	0.37	V
Reverse Leakage Current	$V_R = 30 \text{ V}$	I _R	-	0.5	μA
Junction Capacitance	$V_R = 1V$, $f = 1.0 MHz$	C_{J}	2	-	pF

Note: Valid provided that electrodes are kept at ambient temeprature.



RATINGS AND CHARACTERISTICS CURVES

(T_A=25°C unless otherwise noted)

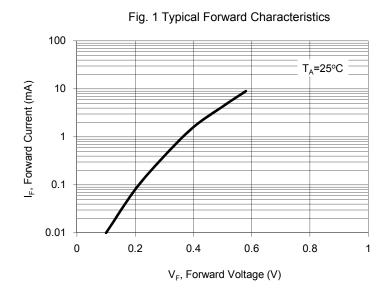
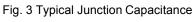


Fig. 2 Admissible Power Dissipation Curve 300 250 Powe Dissipation (mW) 200 150 100 50 50 20 40 0 60 80 100 120 140 Ambient Temperature (°C)



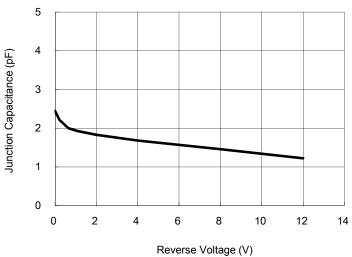
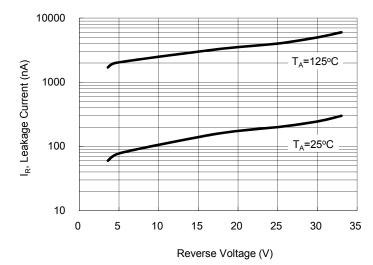
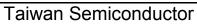


Fig. 4 Typical Reverse Characteristics



Document Number: DS_S1411002





ORDERING INFORMATION						
PART NO.	PART NO.	PACKING	PACKING CODE	PACKAGE	PACKING	
	SUFFIX (Note 1)	CODE	SUFFIX	PACKAGE	PACKING	
RB751V-40WS -xx		RR	G	SOD-323F	3,000 / 7" Reel	
RB/31V-40VV3	-XX	R9	9	30D-323F	10,000 / 13" Reel	

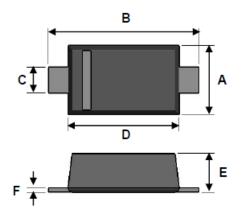
Note 1: Part No. Suffix "-xx " would be used for special requirement

EXAMPLE					
PREFERRED P/N	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
RB751V-40WS RR	RB751V-40WS		RR		Multiple manufacture source
RB751V-40WS RRG	RB751V-40WS		RR	G	Multiple manufacture source Green compound
RB751V-40WS-B0 RRG	RB751V-40WS	-B0	RR	G	Define manufacture source Green compound



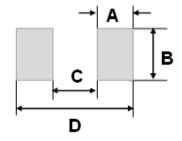
PACKAGE OUTLINE DIMENSIONS

SOD-323F



DIM.	Unit	(mm)	Unit (inch)		
DIIVI.	Min	Max	Min	Max	
Α	1.15	1.35	0.045	0.053	
В	2.30	2.80	0.091	0.110	
С	0.25	0.40	0.010	0.016	
D	1.60	1.80	0.063	0.071	
Е	0.80	1.10	0.031	0.043	
F	0.05	0.25	0.002	0.010	

SUGGEST PAD LAYOUT



DIM.	Unit (mm)	Unit (inch)
DIWI.	Тур.	Тур.
Α	0.63	0.025
В	0.83	0.033
С	1.60	0.063
D	2.86	0.113







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